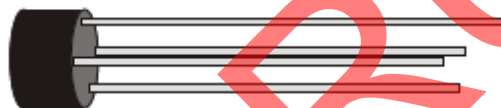


Features

- Ideal for printed circuit board
- Low forward voltage
- Low leakage current
- Glass passivated chip junctions
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals



Mechanical Data

- Case: WOG
- Polarity: marked on body
- Mounting position: Any

Major Ratings and Characteristics

$I_{F(AV)}$	2.0 A
V_{RRM}	50 V to 1000 V
I_{FSM}	60A
V_F	1.1V
T_J max.	150 °C

Maximum Ratings & Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified
Single phase ,half wave, 60Hz,resistive or inductive load
For capacitive load, derate current by 20%.

Items	Symbol	2W005	2W01	2W02	2W04	2W06	2W08	2W10	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current .375"(9.5mm) lead length at $T_A=25^{\circ}\text{C}$	$I_{F(AV)}$	2.0							A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load(JEDEC method)	I_{FSM}	60							A
I^2t Rating for Fusing ($t < 8.3\text{ms}$)	I^2t	15							A ² S
Operating junction temperature range	T_J	-55 to +150							°C
Storage temperature range	T_{STG}	-55 to +150							°C

Electrical Characteristics ($T_A = 25^{\circ}\text{C}$ unless otherwise noted)

Items	Test conditions	Symbol	VALUE	UNIT
Instantaneous forward voltage	$I_F=1.0\text{ A}$	V_F	1.1	V
Reverse current	$V_R=V_{DC}$	I_R	10	μA
	$T_A=100^{\circ}\text{C}$		1	mA

Rating and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

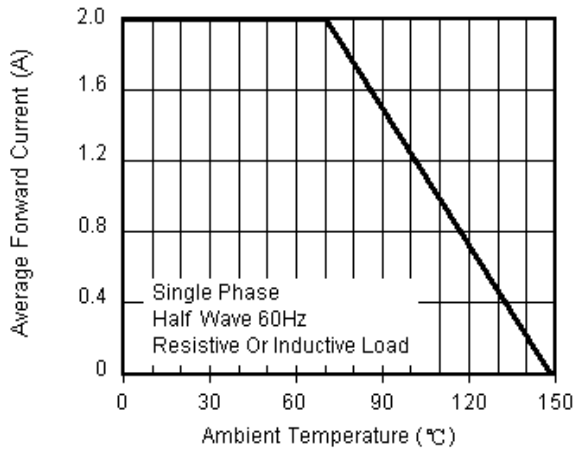


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

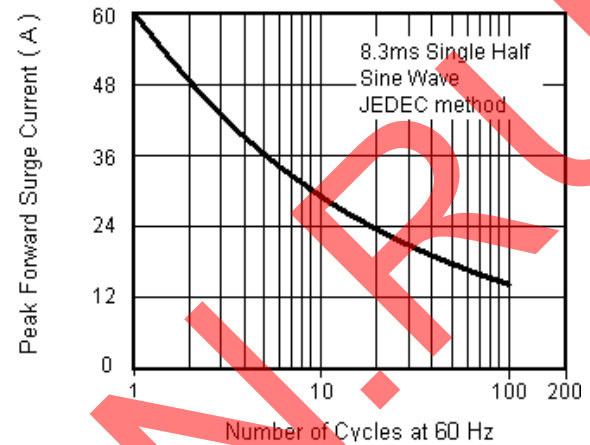


Fig.3 Typical Instantaneous Forward Characteristics

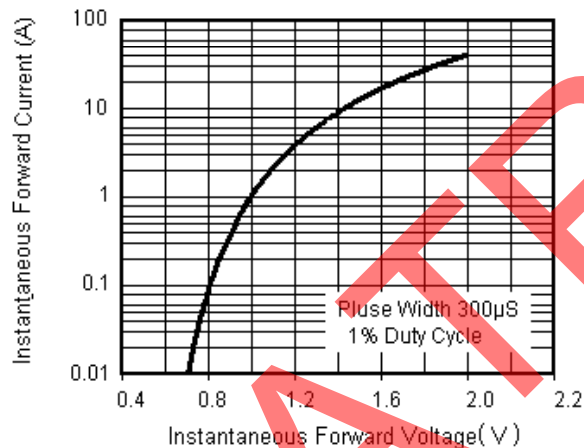
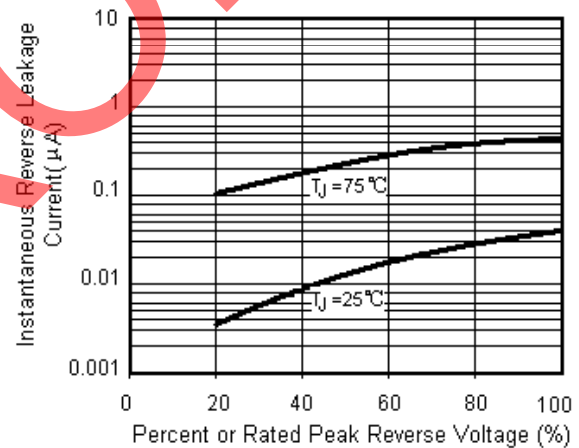
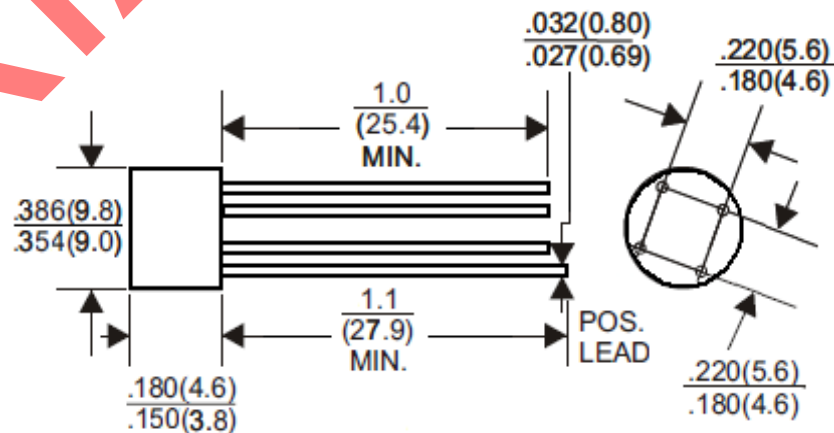


Fig.4 Typical Reverse Leakage Characteristics



Package Outline

WOG



Dimensions in inches and (millimeters)